

ABSTRACT

**ETCHING FLUID FOR FORMING TEXTURE AND TEXTURE-FORMING
METHOD USING SAME**

There are provided a silicon substrate etching fluid and an etching method for forming texture with which a desirable texture can be uniformly and stably formed on a substrate surface without causing the additive components to vaporize in the common working temperature range of 60°C to 95°C, and that is applicable to both a silicon substrate produced by using the loose-abrasive grain method, and a silicon substrate produced by using the fixed-abrasive grain method. The etching fluid includes (A) an alkali component; (B) a phosphonic acid derivative or a salt thereof; and (C) a compound that contains at least one selected from the group consisting of a carboxy group, a sulfo group, a carboxy or sulfo group forming a salt, and a carboxymethyl group.